

SPECIFICATIONS

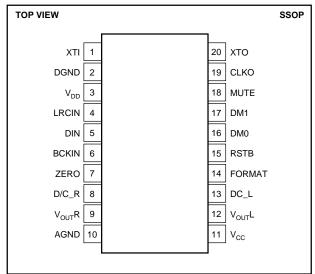
All specifications at +25°C, +V_{CC} = +V_{DD} = +5V, fs = 44.1kHz, and 18-bit input data, SYSCLK = 384fs, unless otherwise noted. Measurement bandwidth is 20kHz.

			PCM1718E			
PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS	
RESOLUTION		16		18	Bits	
DIGITAL INPUT/OUTPUT						
Logic Family			CMOS			
Input Logic Level:						
V _{IH} ⁽²⁾		70% of V_{DD}			V	
V _{IL} ⁽²⁾				30% of V_{DD}	V	
V _{IH} ⁽³⁾		70% of V_{DD}			V	
V _{IL} ⁽³⁾				30% of V_{DD}	V	
V _{IH} ⁽⁴⁾		64% of V_{DD}			V	
V _{IL} ⁽⁴⁾				28% of V _{DD}	V	
Input Logic Current:					Ι.	
_{IH} (5)				-6.0	μΑ	
_{IL} (5)				-120	μΑ	
I _{IH} (6)				-2	μΑ	
I _{IL} (6)				0.02	μΑ	
	$V_{IN} = 3.2V$			40	μΑ	
I _{IL} ⁽⁴⁾	$V_{IN} = 1.4V$	1		-40	μΑ	
Output Logic Level: $(+V_{DD} = +5V)$					l	
V _{OH} ⁽⁷⁾	$I_{OH} = -5mA$	3.8			V	
V _{OL} ⁽⁷⁾	$I_{OL} = +5mA$			1.0	V	
V _{OL} ⁽⁸⁾	I _{OL} = +5mA			1.0	V	
Interface Format			electable Normal,			
Data Format			B First Binary Two			
Sampling Frequency		32	44.1	48	kHz	
System Clock Frequency	256fs/384fs	8.192/12.288	11.2896/16.9344	12.288/18.432	MHz	
DC ACCURACY						
Gain Error			±1.0	±5.0	% of FSF	
Gain Mismatch Channel-to-Channel			±1.0	±5.0	% of FSF	
Bipolar Zero Error	V _O = 1/2 V _{CC} at Bipolar Zero		±30		mV	
DYNAMIC PERFORMANCE ⁽¹⁾	V _{CC} = +5V, f = 991Hz					
THD+N at FS (0dB)	100, 1 = 001112		-90	-80	dB	
THD+N at -60dB			-34		dB	
Dynamic Range	EIAJ, A-weighted	90	96		dB	
Signal-To-Noise Ratio	EIAJ, A-weighted	92	100		dB	
Channel Separation	El lo, / Wolghod	90	97		dB	
Level Linearity Error (-90dB)		00	±0.5		dB	
	V _{CC} = +3V, f = 991Hz					
THD+N at FS (0dB)	VCC = 10V, 1 = 001112		-86		dB	
Dynamic Range	EIAJ, A-weighted		91		dB	
Signal-To-Noise Ratio	EIAJ, A-weighted		94		dB	
•	Elito, A Wolghiou		01		uD	
				10.17		
Pass Band Ripple		05		±0.17	dB	
Stop Band Attenuation		-35		0.445	dB	
Pass Band		0.555		0.445	fs	
Stop Band	<i>"</i> ()	0.555		0.55	fs	
De-emphasis Error	(fs = 32kHz ~ 48kHz)	-0.2	44 405%-	+0.55	dB	
Delay Time (Latency)			11.125/fs		sec	
ANALOG OUTPUT		1				
Voltage Range	FS (0dB) OUT	1	62% of V_{CC}		Vp-p	
Load Impedance		5			kΩ	
Center Voltage			50% of V _{CC}		V	
		1				
POWER SUPPLY REQUIREMENTS	+V _{CC}	+2.7		+5.5	VDC	
		+2.7		+5.5	VDC	
	+V _{DD}	12.7				
Voltage Range:	$+V_{CC} = +V_{DD} = +5V$	12.1	18.0	25.0	mA	
Voltage Range:	$+V_{CC} = +V_{DD} = +5V$	12.1	18.0 9.0	25.0 15.0	mA mA	
Voltage Range: Supply Current: +I _{CC} +I _{DD} ⁽⁹⁾	$+V_{CC} = +V_{DD} = +5V$ $+V_{CC} = +V_{DD} = +3V$	12.1				
Voltage Range: Supply Current: +I _{CC} +I _{DD} ⁽⁹⁾	$+V_{CC} = +V_{DD} = +5V$ $+V_{CC} = +V_{DD} = +3V$ $+V_{CC} = +V_{DD} = +5V$		9.0	15.0	mA	
POWER SUPPLY REQUIREMENTS Voltage Range: Supply Current: +I _{CC} +I _{DD} ⁽⁹⁾ Power Dissipation	$+V_{CC} = +V_{DD} = +5V$ $+V_{CC} = +V_{DD} = +3V$		9.0 90	15.0 125	mA mW	
Voltage Range: Supply Current: +I _{CC} +I _{DD} ⁽⁹⁾	$+V_{CC} = +V_{DD} = +5V$ $+V_{CC} = +V_{DD} = +3V$ $+V_{CC} = +V_{DD} = +5V$	-25	9.0 90	15.0 125	mA mW	

NOTES: (1) Tested with Shibasoku #725 THD. Meter 400Hz HPF, 30kHz LPF On, Average Mode with 20kHz bandwidth limiting. (2) Pins 4, 5, 6, 14: LRCIN, DIN, BCKIN, FORMAT. (3) Pins 15, 16, 17, 18: RSTB, DM0, DM1, MUTE (Schmitt trigger input). (4) Pin 1: XTI. (5) Pins 15, 16, 17, 18: RSTB, DM0, DM1, MUTE (if pull-up resistor is used). (6) Pins 4, 5, 6: LRCIN, DIN, BCKIN (if pull-up resistor is not used). (7) Pin 19: CLKO. (8) Pin 7: ZERO. (9) No load on pins 19 (CLKO) and 20 (XTO).



PIN CONFIGURATION



PACKAGE INFORMATION

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾
PCM1718E	20-Pin SSOP	334-1

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book.

ABSOLUTE MAXIMUM RATINGS

Power Supply Voltage	+6 5\/
+V _{CC} to +V _{DD} Difference	±0.1V
Input Logic Voltage	–0.3V to (V _{DD} + 0.3V)
Power Dissipation	200mW
Operating Temperature Range	25°C to +85°C
Storge Temperature	–55°C to +125°C
Lead Temperature (soldering, 5s)	+260°C
Thermal Resistance, θ_{JA}	+70°C/W

PIN ASSIGNMENTS

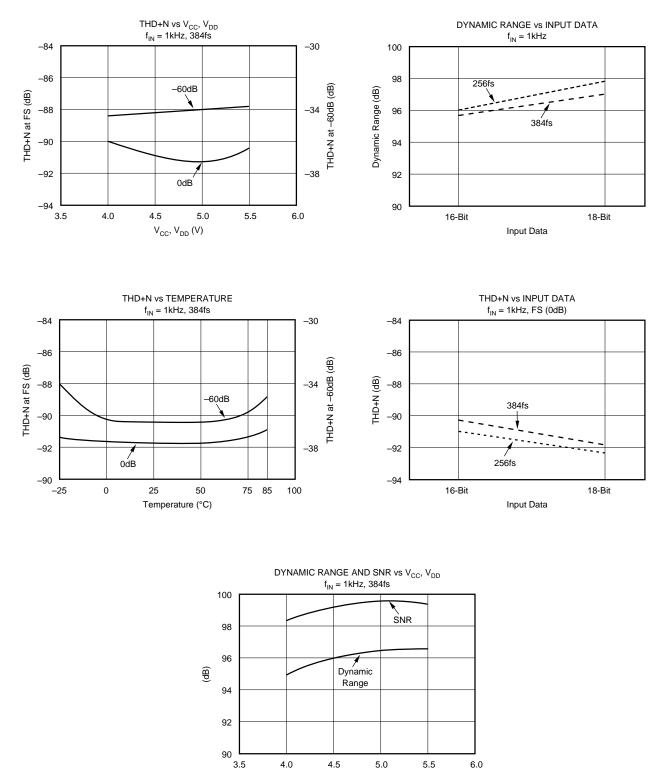
PIN	NAME	FUNCTION
Data	Input Inter	face Pins
4 5	LRCIN DIN	Sample Rate Clock Input. Controls the update rate (fs). Serial Data Input. MSB first, right justified (Sony format, 18 bits) or I ² S (Philips format, 16 or 18 bits).
6	BCKIN	Bit Clock Input. Clocks in the data present on DIN input.
Mode	e Control a	nd Clock Signals
1	XTI	Oscillator Input (External Clock Input). For an internal clock, tie XTI to one side of the crystal oscillator. For an external clock, tie XTI to the output of the chosen external clock.
14(1)	FORMAT	A "HIGH" selects I ² S input data format, and a "LOW" selects Normal (Sony) input data format.
16(1)	DM0	De-emphasis selection.
17 ⁽¹⁾	DM1	De-emphasis selection.
18 ⁽¹⁾	MUTE	Soft Mute Control. When set "LOW", the outputs are muted.
19	CLKO	Buffered Output of Oscillator. Equivalent to XTI.
20	ХТО	Oscillator Output. When using the internal clock, tie to the opposite side (from pin 1) of the crystal oscillator. When using an external clock, leave XTO open.
Oper	ational Cor	trols and Flags
7	ZERO	Infinite Zero Detection Flag, open drain output. When the input is continuously zero for 65,536 cycles of BCKIN, ZERO is "LOW".
15 ⁽¹⁾	RSTB	Resets DAC operation with an active "LOW" pulse.
Analo	og Output I	Functions
8	D/C_R	Right Channel Output Amplifier Common. Bypass to ground with $10\mu F$ capacitor.
9	V _{OUT} R	Right Channel Analog Output. V_{OUT} max = 0.62 x V_{CC} .
12	V _{OUT} L	Left Channel Analog Output. V_{OUT} max = 0.62 x V_{CC} .
13	D/C_L	Left Channel Output Amplifier Common. Bypass to ground with $10\mu\text{F}$ capacitor.
Powe	er Supply C	connections
2	DGND	Digital Ground.
3	V _{DD}	Digital Power Supply (+5V or +3V).
10	AGND	Analog Ground.
11	V _{CC}	Analog Power Supply (+5V or +3V).
NOT	E: (1) With i	internal pull-up.

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TYPICAL PERFORMANCE CURVES

At T_A = +25°C, V_S = +5V, R_L = 100 Ω , C_L = 2pF, and R_{FB} = 402 Ω , unless otherwise noted. **DYNAMIC PERFORMANCE**



 $\rm V_{CC},\, V_{DD}$

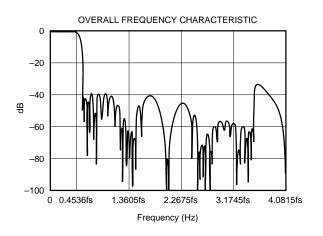
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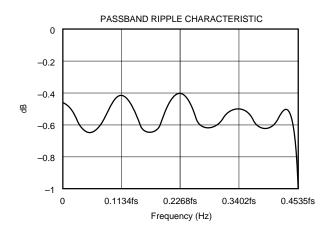


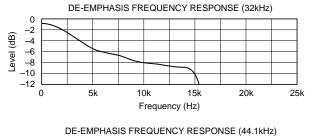
PCM1718E

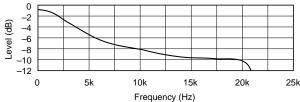
TYPICAL PERFORMANCE CURVES

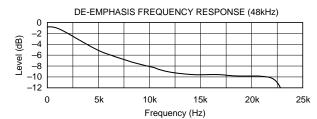
At T_A = +25°C, V_S = +5V, R_L = 44.1kHz, f_{SYS} = 384fs, and 18-bit input data, unless otherwise noted. **DIGITAL FILTER**

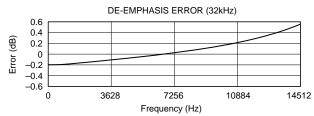




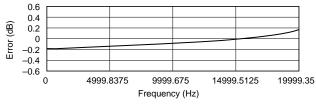


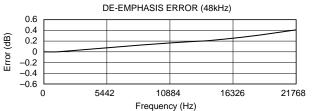














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SYSTEM CLOCK

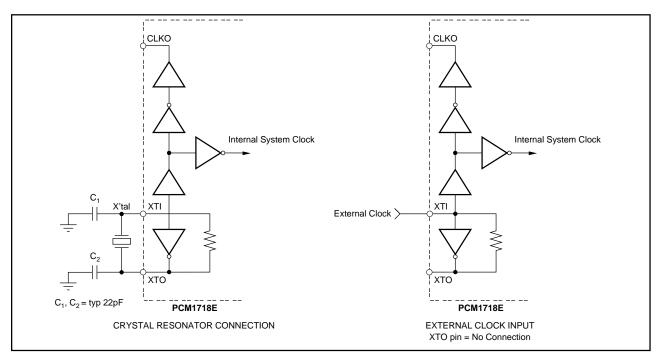
The system clock for PCM1718 must be either 256fs or 384fs, where fs is the audio sampling frequency (typically 32kHz, 44.1kHz, or 48kHz). The system clock is used to operate the digital filter and the modulator.

The system clock can be either a crystal oscillator placed between XTI (pin 1) and XTO (pin 20), or an external clock input to XTI. If an external system clock is used, XTO is open (floating). Figure 1 illustrates the typical system clock connections.

PCM1718 has a system clock detection circuit which automatically senses if the system clock is operating at 256fs or 384fs. The system clock should be synchronized with LRCIN (pin 4) clock. LRCIN (left-right clock) operates at the sampling frequency fs. In the event these clocks are not synchronized, PCM1718 can compensate for the phase difference internally. If the phase difference between left-right and system clocks is greater than 6 bit clocks (BCKIN), the synchronization is performed internally. While the synchronization is processing, the analog output is forced to a DC level at bipolar zero. The synchronization typically occurs in less than 1 cycle of LRCIN.

DATA INTERFACE FORMATS

Digital audio data is interfaced to PCM1718 on pins 4, 5, and 6—LRCIN (left-right clock), DIN (data input) and BCKIN (bit clock). PCM1718 can accept both normal and I²S data formats. Normal data format is MSB first, two's complement, right-justified. I²S data is compatible with Philips serial data protocol. Figures 3 and 4 illustrate the input data formats.





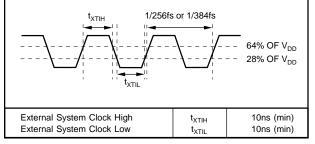


FIGURE 2. External Clock Timing Requirements.

FUNCTIONAL CONTROLS

PCM1718 allows the user to control the input data format, soft mute, and digital de-emphasis frequency. Table I illustrates the selectable functions:

FUNCTION	CONTROL PIN
Data Input Format Normal I ² S	FORMAT (Pin 14)
De-emphasis 32kHz 44.1kHz 48kHz	DM0, DM1 (Pins 16, 17)
Soft Mute	MUTE (Pin 18)
Reset	RSTB (Pin 15)

TABLE I. Selectable Functions.



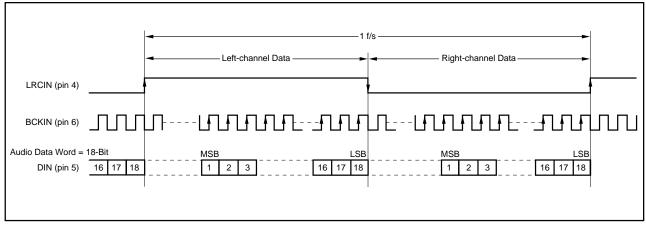


FIGURE 3. "Normal" Data Input Timing.

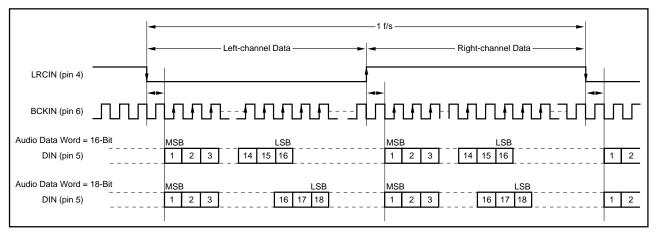


FIGURE 4. "I²S" Data Input Timing.

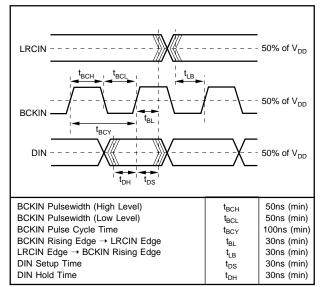


FIGURE 5. Data Input Timing.

Data Format

A "HIGH" on pin 14 (FORMAT) sets the input format to I²S, and a "LOW" sets the format to Normal (MSB-first, right-justified Sony format).

Soft Mute

A "LOW" on pin 18 (MUTE) causes both outputs to be muted. This muting is done in the digital domain so there is no audible "click" when the soft mute is enacted.

De-Emphasis

PCM1718 allows for digital de-emphasis for all three standard sampling frequencies:

DM1 (Pin 17)	DM0 (Pin 16)	De-Emphasis Mode
0	0	OFF
0	1	48kHz
1	0	44.1kHz
1	1	32kHz

Reset

PCM1718 has both internal power on reset circuit and the RSTB-pin (pin 15) which accepts external forced reset by RSTB = LOW. For internal power on reset, initialize (reset) is done automatically at power on $V_{DD} > 2.2V$ (typ). During internal reset = LOW, the output of the DAC is invalid and the analog outputs are forced to $V_{CC}/2$. Figure 6 illustrates the timing of internal power on reset.

For the RSTB-pin, PSTB-pin accepts external forced reset by RSTB = L. During RSTB = L, the output of the DAC is invalid and the analog outputs are forced to $V_{CC}/2$ after internal initialize (1024 system clocks count after RSTB = H.) Figure 7 illustrates the timing of RSTB-pin reset.

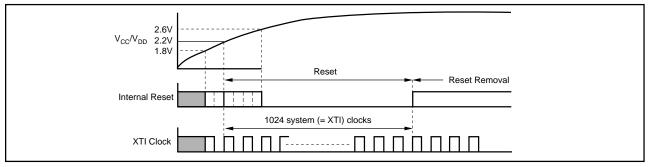


FIGURE 6. Internal Power-On Reset Timing.

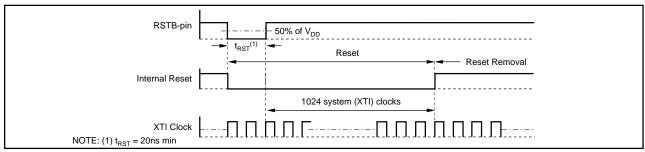


FIGURE 7. RSTB-Pin Reset Timing.

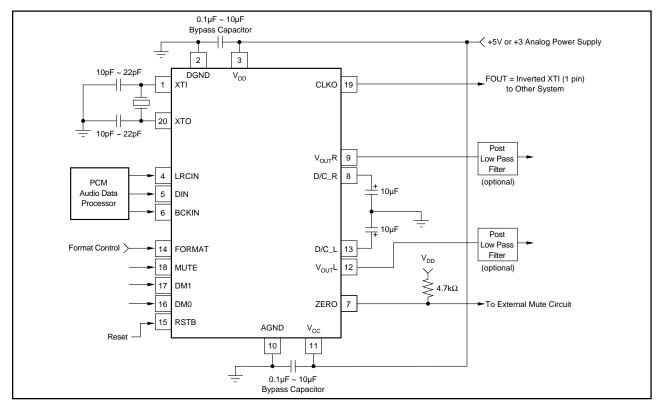


FIGURE 8. Typical Connection Diagram of PCM1718.

PCM1718E



POWER SUPPLY CONNECTIONS

PCM1718 has two power supply connections: digital (V_{DD}) and analog (V_{CC}). Each connection also has a separate ground. If the power supplies turn on at different times, there is a possibility of a latch-up condition. To avoid this condition, it is recommended to have a common connection between the digital and analog power supplies. If separate supplies are used without a common connection, the delta between the two supplies during ramp-up time must be less than 0.6V.

An application circuit to avoid a latch-up condition is shown in Figure 9.

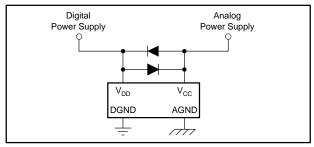


FIGURE 9. Latch-up Prevention Circuit.

BYPASSING POWER SUPPLIES

The power supplies should be bypassed as close as possible to the unit. Refer to Figure 8 for optimal values of bypass capacitors.

THEORY OF OPERATION

The delta-sigma section of PCM1718 is based on a 5-level amplitude quantizer and a 3rd-order noise shaper. This section converts the oversampled input data to 5-level deltasigma format. A block diagram of the 5-level delta-sigma modulator is shown in Figure 10. This 5-level delta-sigma modulator has the advantage of stability and clock jitter sensitivity over the typical one-bit (2 level) delta-sigma modulator.

The combined oversampling rate of the delta-sigma modulator and the internal 8-times interpolation filter is 48fs for a 384fs system clock, and 64fs for a 256fs system clock. The theoretical quantization noise performance of the 5-level delta-sigma modulator is shown in Figure 11.



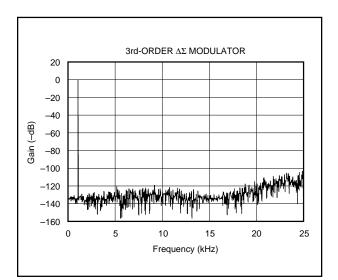


FIGURE 11. Quantization Noise Spectrum.

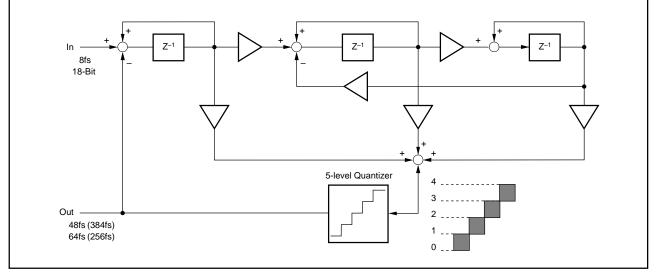


FIGURE 10. 5-Level $\Delta\Sigma$ Modulator Block Diagram.



APPLICATION CONSIDERATIONS

DELAY TIME

There is a finite delay time in delta-sigma converters. In A/D converters, this is commonly referred to as latency. For a delta-sigma D/A converter, delay time is determined by the order number of the FIR filter stage, and the chosen sampling rate. The following equation expresses the delay time of PCM1718:

 $T_D = 11.125 \text{ x } 1/\text{fs}$

For fs = 44.1 kHz, $T_D = 11.125/44.1 \text{kHz} = 251.4 \mu \text{s}$

Applications using data from a disc or tape source, such as CD audio, CD-Interactive, Video CD, DAT, Minidisc, etc., generally are not affected by delay time. For some professional applications such as broadcast audio for studios, it is important for total delay time to be less than 2ms.

OUTPUT FILTERING

For testing purposes all dynamic tests are done on the PCM1718 using a 20kHz low pass filter. This filter limits the measured bandwidth for THD+N, etc. to 20kHz. Failure to use such a filter will result in higher THD+N and lower SNR and Dynamic Range readings than are found in the specifications. The low pass filter removes out of band noise. Although it is not audible, it may affect dynamic specification numbers.

The performance of the internal low pass filter from DC to 24kHz is shown in Figure 12. The higher frequency rolloff of the filter is shown in Figure 13. If the user's application has the PCM1718 driving a wideband amplifier, it is recommended to use an external low pass filter. A simple 3rd-order filter is shown in Figure 14. For some applications, a passive RC filter or 2nd-order filter may be adequate.

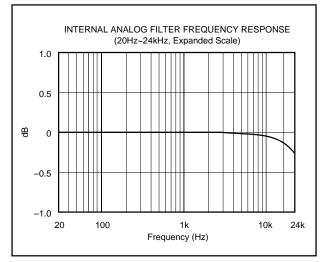


FIGURE 12. Low Pass Filter Frequency Response.

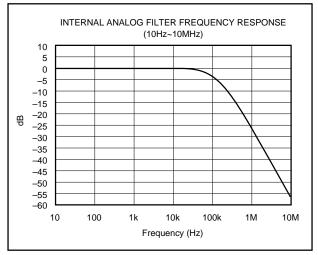


FIGURE 13. Low Pass Filter Frequency Response.

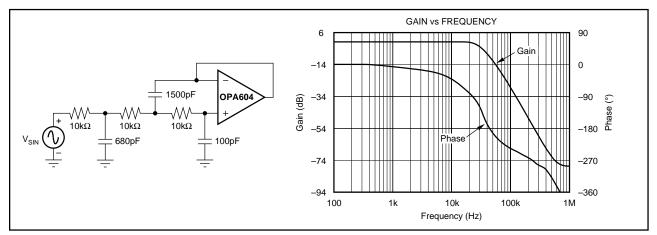


FIGURE 14. 3rd-Order LPF.



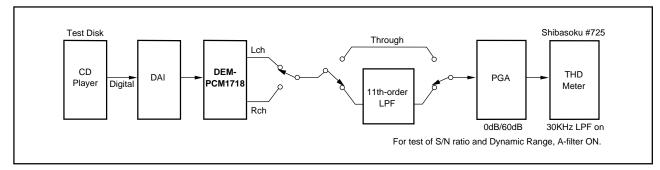


FIGURE 15. Test Block Diagram.

TEST CONDITIONS

Figure 15 illustrates the actual test conditions applied to PCM1718 in production. The 11th-order filter is necessary in the production environment for the removal of noise resulting from the relatively long physical distance between the unit and the test analyzer. In most actual applications, the 3rd-order filter shown in Figure 14 is adequate. Under normal conditions, THD+N typical performance is -70dB with a 30kHz low pass filter (shown here on the THD meter), improving to -89dB when the external 20kHz 11th-order filter is used. For cost-sensitive applications, a single RC filter, as shown in Figure 18, may be adequate.

EVALUATION FIXTURES DEM-PCM1718

This evaluation fixture is primarily intended for quick evaluation of the PCM1718's performance. DEM-PCM1718 can accept either an external clock or a user-installed crystal oscillator. All of the functions can be controlled by on-board switches. DEM-PCM1718 does not contain a receiver chip or an external low pass filter. DEM-PCM1718 requires a single +2.7V to +5V power supply.

OUT-OF-BAND NOISE CONSIDERATIONS

Delta-sigma DACs are by nature very sensitive to jitter on the master clock. Phase noise on the clock will result in an increase in noise, ultimately degrading dynamic range. It is difficult to quantify the effect of jitter due to problems in synthesizing low levels of jitter. One of the reasons deltasigma DACs are prone to jitter sensitivity is the large quantization noise when the modulator can only achieve two discrete output levels (0 or 1). The multi-level delta-sigma DAC has improved theoretical SNR because of multiple output states. This reduces sensitivity to jitter. Figure 16 contrasts jitter sensitivity between a one-bit PWM type DAC and multi-level delta-sigma DAC. The data was derived using a simulator, where clock jitter could be completely synthesized.

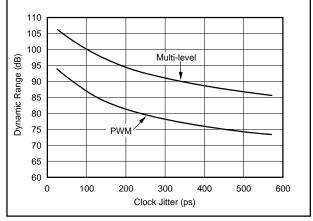


FIGURE 16. Simulation Results of Clock Jitter Sensitivity.

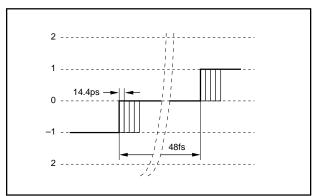


FIGURE 17. Simulation Method for Clock Jitter.

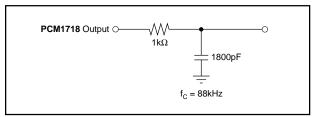


FIGURE 18. RC Output Filter.





24-Apr-2015

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
PCM1718E	NRND	SSOP	DB	20	65	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PCM1718E	
PCM1718E/2K	NRND	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PCM1718E	
PCM1718EG4	NRND	SSOP	DB	20	65	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PCM1718E	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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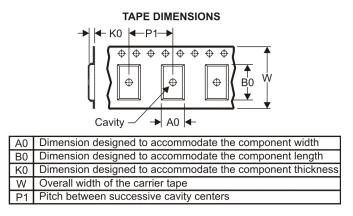
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All	dimensions	are	nominal
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Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PCM1718E/2K	SSOP	DB	20	2000	330.0	17.4	8.5	7.6	2.4	12.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

13-Jun-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PCM1718E/2K	SSOP	DB	20	2000	336.6	336.6	28.6

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